#### Continued from preceding page.

Parameter	Symbol	Conditions	Ratings	Unit
Allowable power dissipation	Pd max	Mounted on a specified board *	800	mW
Operating temperature	Topr		-30 to +85	°C
Storage temperature	Tstg		-55 to +150	°C

<sup>\*</sup> Specified board: 114.3mm  $\times$  76.1mm  $\times$  1.5mm, glass epoxy board.

#### Allowable Operating Ranges at Ta = 25°C

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	VCC		2.2 to 10.8	V
High-level input voltage	V <sub>IH</sub>		2.0 to 10	V
Low-level input voltage	V <sub>IL</sub>		-0.3 to +0.3	V

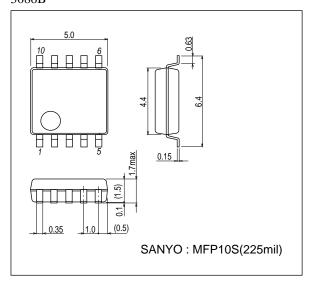
### **Electrical Characteristics** at Ta = 25°C, $V_{CC} = 3V$

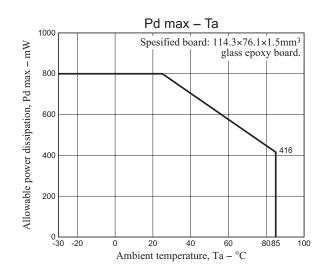
Parameter	0 1 1	0	Ratings			11.7
	Symbol	Symbol Conditions	min	typ	max	Unit
Current drain	I <sub>CC</sub> 1	Standby mode		0.1	5	μА
	I <sub>CC</sub> 2	Forward or reverse drive operation		15	21	mA
	ICC3	Braking		22	31	mA
Output saturation voltage	V <sub>O</sub> (sat)1	Forward or reverse drive: High side + low side, I <sub>O</sub> = 200mA			0.35	V
	V <sub>O</sub> (sat)2	Forward or reverse drive: High side + low side, I <sub>O</sub> = 500mA		0.55	0.75	V
	V <sub>O</sub> (sat)3	Forward or reverse drive: High side only, I <sub>O</sub> = 200mA		0.15	0.25	V
Input current	I <sub>IN</sub>	V <sub>IN</sub> = 5V		70	95	μА
Thermal detection operating temperature	THD	Design guarantee value*	150	180	200	°C
Spark killer diode					•	•
Forward voltage	VSF	I <sub>O</sub> = 200mA		0.9	1.7	V
Reverse current	I <sub>RS</sub>	V <sub>OUT</sub> = 10V		0.1	5	μА

<sup>\*</sup> Design guarantee value, Do not measurement.

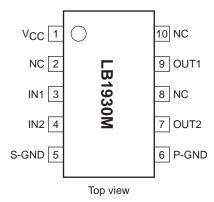
## **Package Dimensions**

unit : mm (typ) 3086B

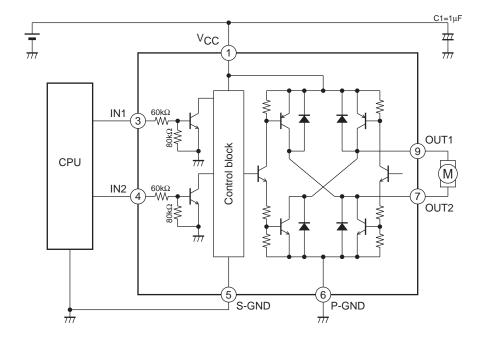




## **Pin Assignment**

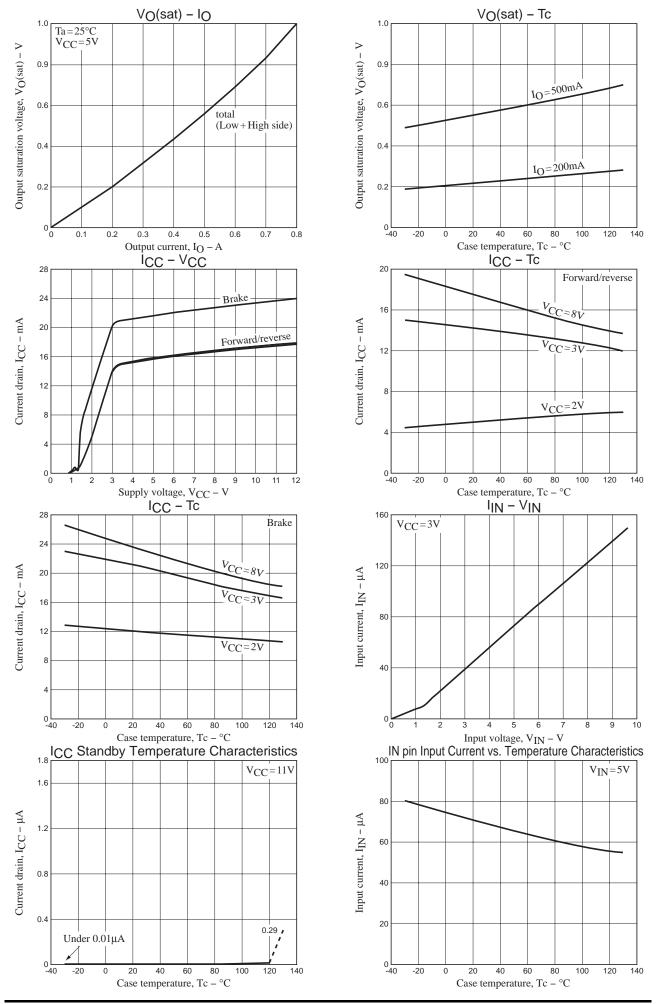


# **Block Diagram and Application Circuit Example**



### **Truth Table**

IN1	IN2	OUT1	OUT2	Mode
L	L	OFF	OFF	Standby
Н	L	Н	L	Forward
L	Н	L	Н	Reverse
Н	Н	Н	Н	Brake



#### **Usage Notes**

Oscillation may occur in the V<sub>CC</sub> and P-GND lines, since these lines carry a wide range of currents. The following may help if this is a problem.

- (1) Lower the inductance of the wiring by making lines wider and shorter.
- (2) Insert capacitors with good frequency characteristics close to the IC.
- (3) Consider adopting the following methods if the CPU and this IC are mounted on different printed circuit boards that could easily have different ground potentials.
  - Connect S-GND to the CPU ground and connect P-GND to the power system ground.
  - Insert resistors of about  $10k\Omega$  in series between the controller outputs and the inputs on this IC.

- SANYO Semiconductor Co.,Ltd. assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all SANYO Semiconductor Co.,Ltd. products described or contained herein.
- SANYO Semiconductor Co.,Ltd. strives to supply high-quality high-reliability products, however, any and all semiconductor products fail or malfunction with some probability. It is possible that these probabilistic failures or malfunction could give rise to accidents or events that could endanger human lives, trouble that could give rise to smoke or fire, or accidents that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all SANYO Semiconductor Co.,Ltd. products described or contained herein are controlled under any of applicable local export control laws and regulations, such products may require the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written consent of SANYO Semiconductor Co.,Ltd.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the SANYO Semiconductor Co.,Ltd. product that you intend to use.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.
- Upon using the technical information or products described herein, neither warranty nor license shall be granted with regard to intellectual property rights or any other rights of SANYO Semiconductor Co.,Ltd. or any third party. SANYO Semiconductor Co.,Ltd. shall not be liable for any claim or suits with regard to a third party's intellectual property rights which has resulted from the use of the technical information and products mentioned above.

This catalog provides information as of June, 2011. Specifications and information herein are subject to change without notice.